

Direct Electron Detectors with DEPFETs

Rainer Richter

for the MPG Halbleiterlabor

Requirements on an electron detector and how they can be fulfilled
with DEPFETs

Focus on real space applications (80kHz detector)

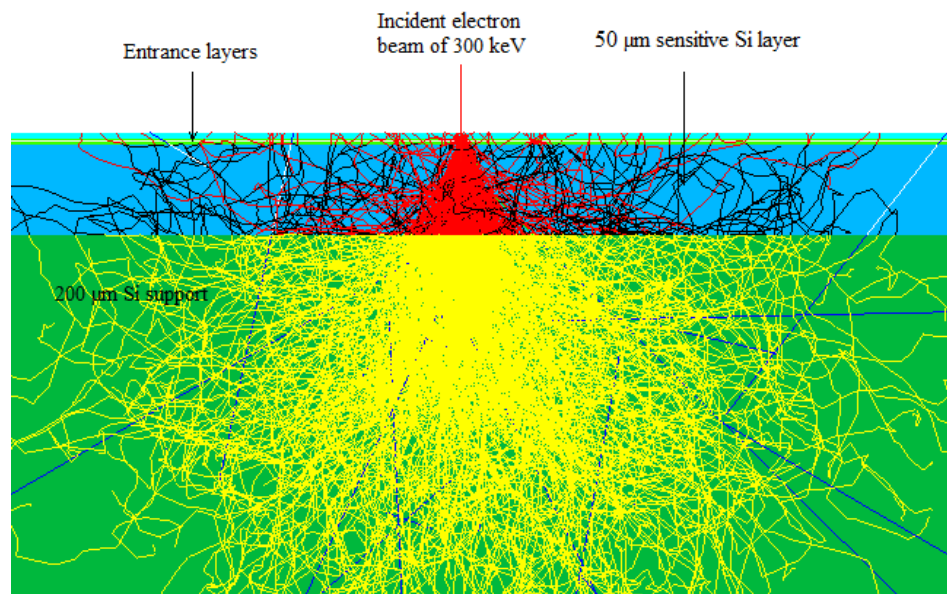
Direct Electron Detectors with Depfets ?

What is needed?

1. thin detector

50 μ m thick detector

With 200 μ m pass. Si support structure



300keV electron beam, MC Geant4 by Ibrahim Dourki

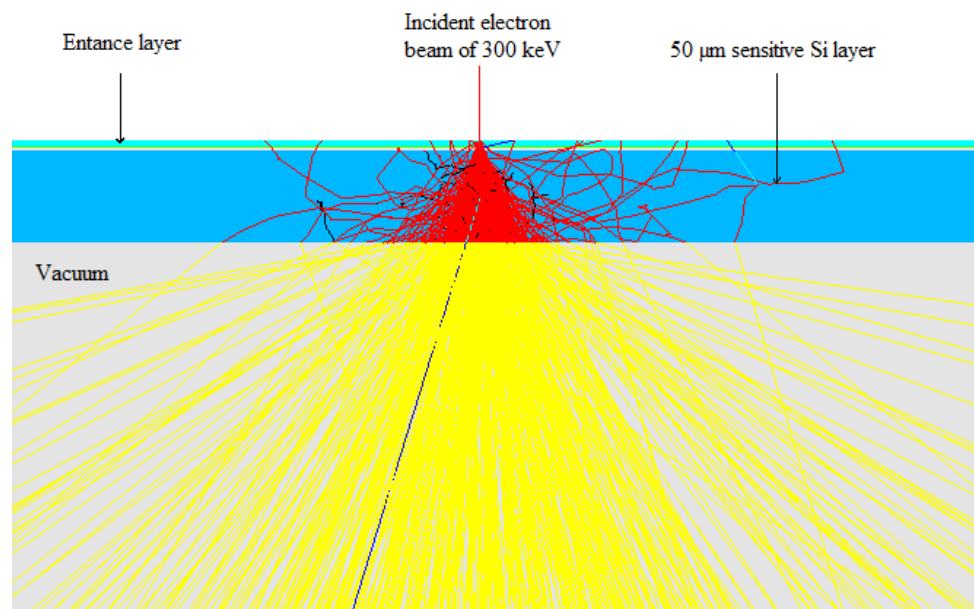
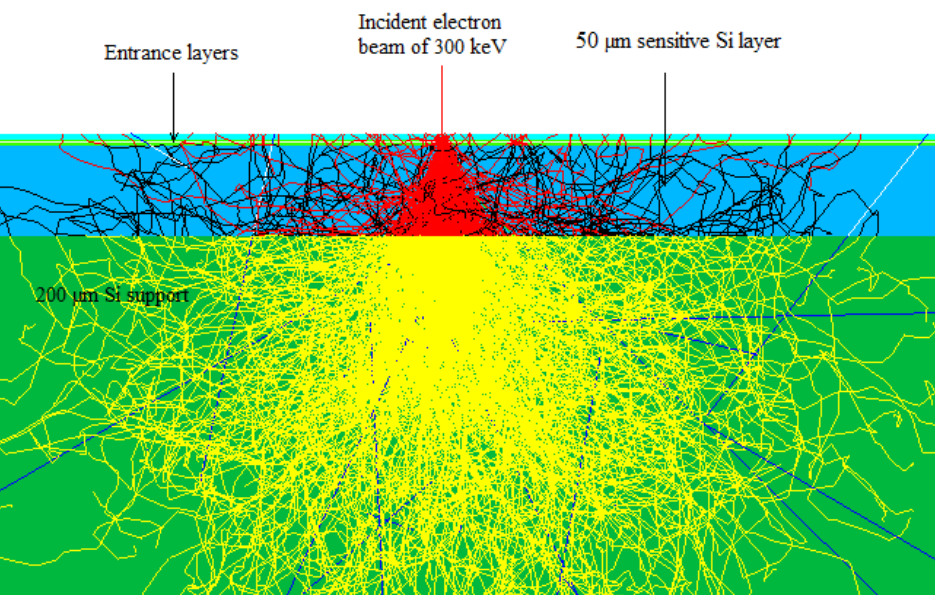
Direct Electron Detectors with Depfets ?

What is needed?

1. thin detector

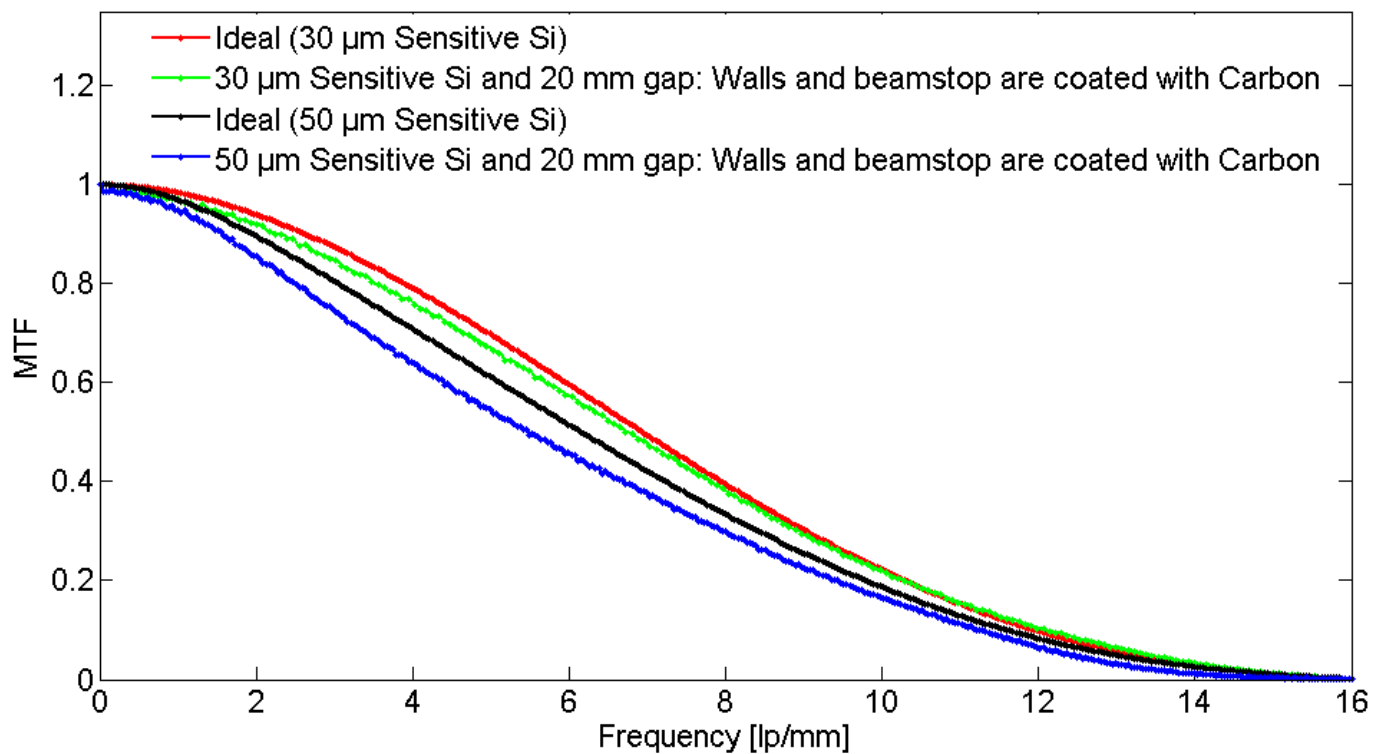
50 μ m thick detector
with 200 μ m pass. Si support structure

50 μ m thick detector
without 200 μ m support structure
carbon beam stop 20mm beneath



works only at very low power consumption !

Modulation Transfer Function (MTF)



- 2. Low noise - single electron detection if possible

No problem

1 primary electron in 50um Si

-> about 5000 e/h

Well known from Belle2 pixel detector even at high speed 😊

Low noise of DEPFET – small Internal Gate capacitance !!

- 2. High speed

as in Belle ...

- 100ns row processing time (DCD)
- 4-fold readout

512 x 512 sensor array (currently in production)

-> 12.5 μ s (80kHz)

- 4. high dynamic range (i)

Sascha Epp:
50 better 100 primary electrons



▶ 100 el/px Poisson only



▶ 100 keV

▶ pitch black = 1000 A sample

▶ very white = 0 A sample

▶ 0..1000A in 256 steps

- 4. High dynamic range (ii)

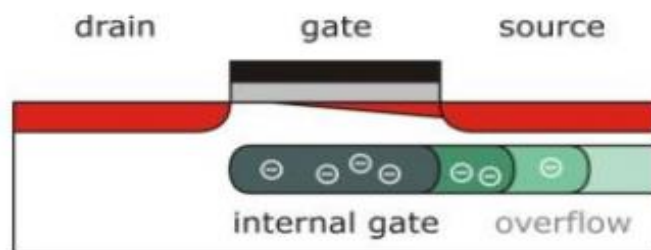
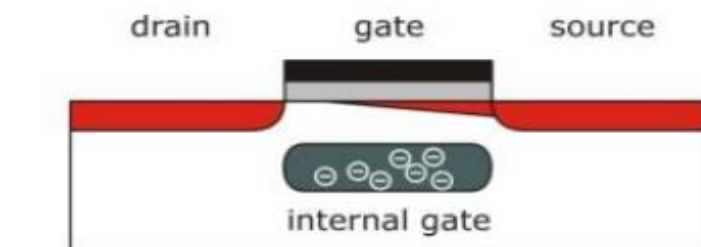
100 primary e- (300keV, 50um) -> 500 000 signal e- to be stored

Charge handling capacity of a Belle DEPFET: 50 000 e- 

Very small Internal Gate capacitance ...

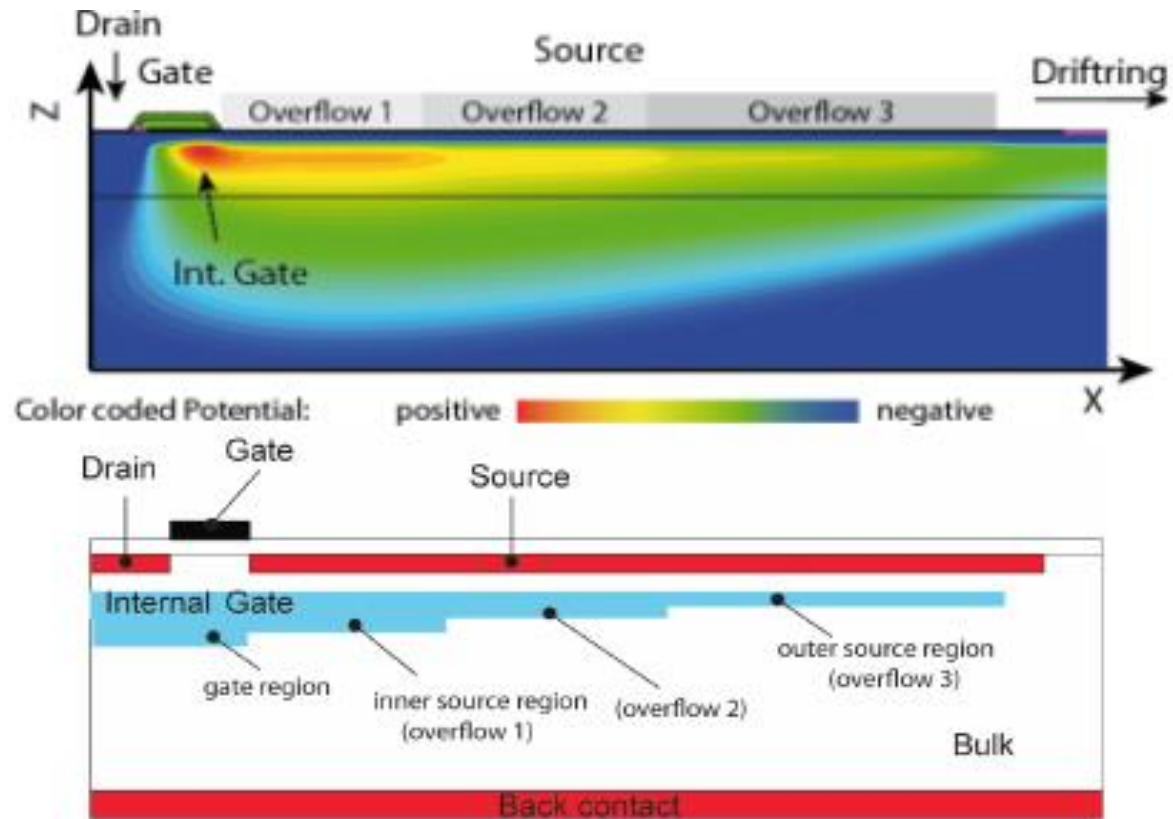
DEPFET technology
offers a simple natural solution

● What happens if the Internal Gate is full?



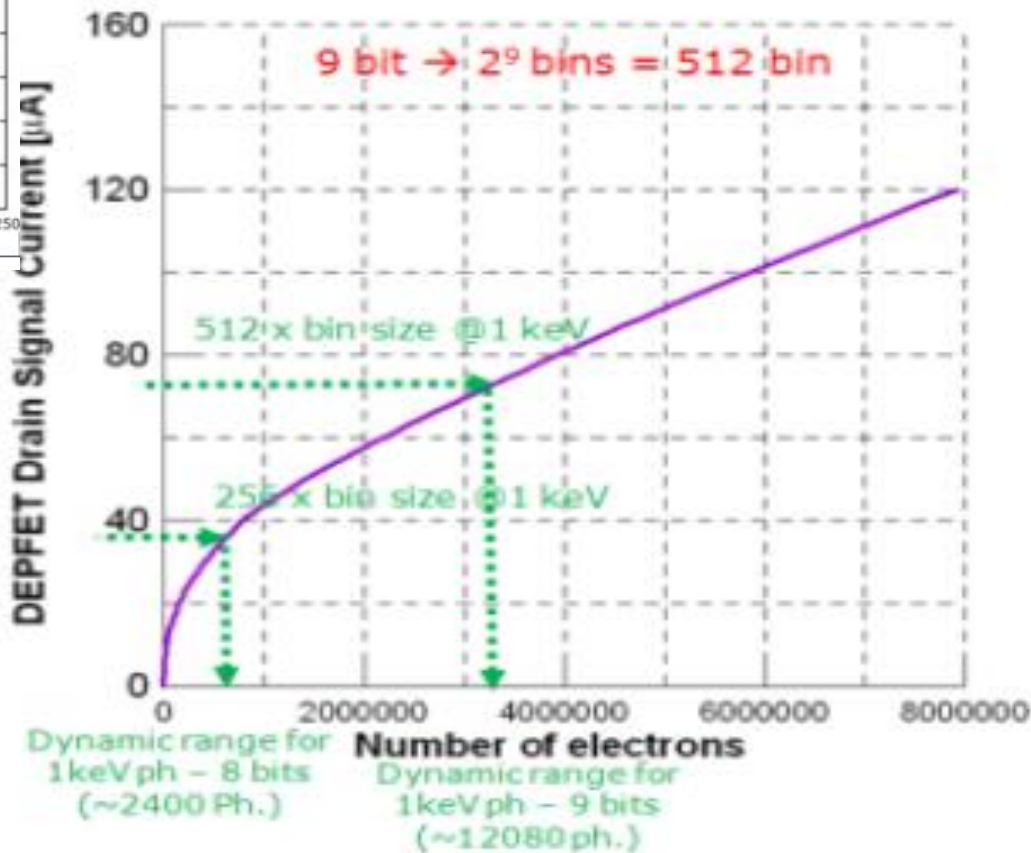
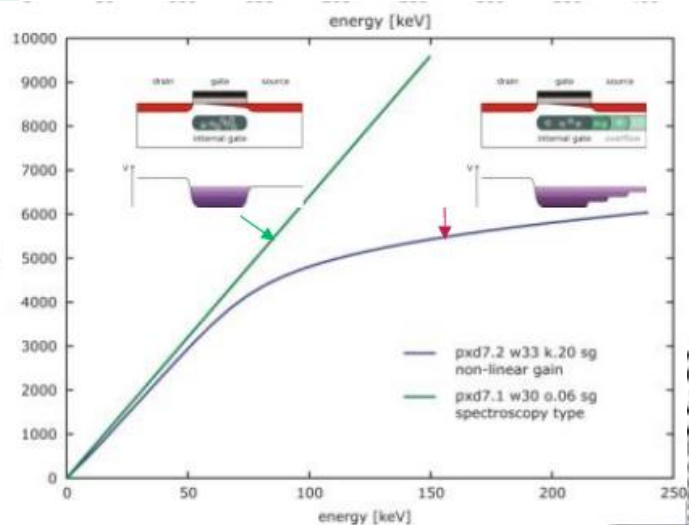
Pictures taken from DSSC-Project

The DSSC-DEPFET for the XFEL Project



Input capacitance increases if charge spills over

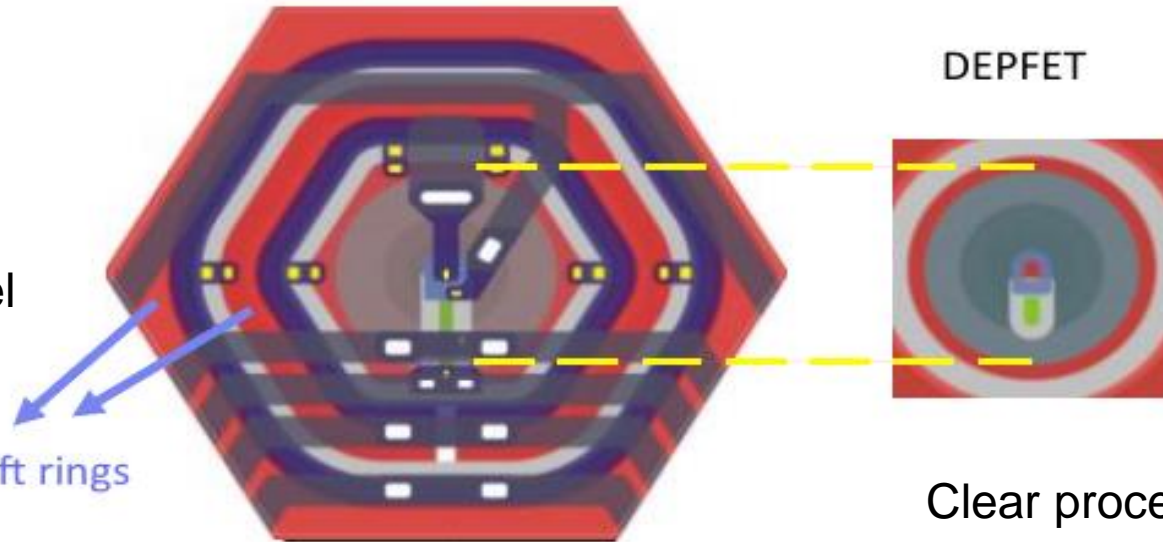
DEPFET response: charge storage and signal compression at once



- DSSC concept suitable for electron detection?

Pixel size 200 μ m!

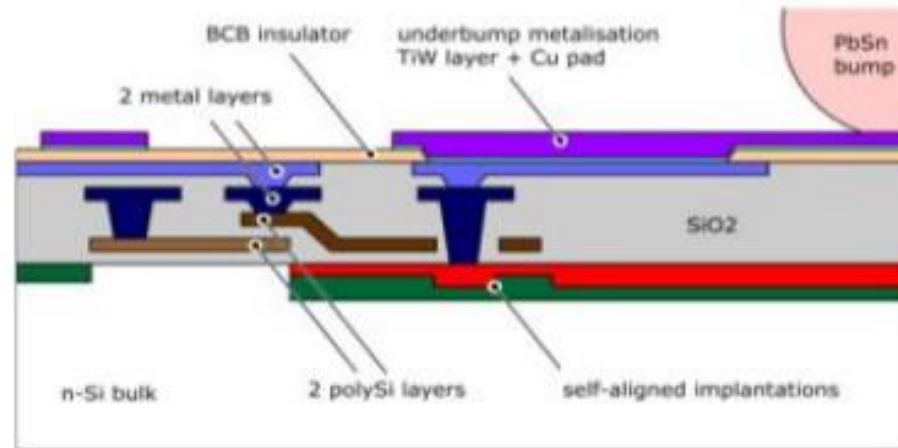
Much smaller pixel required



Clear process slow



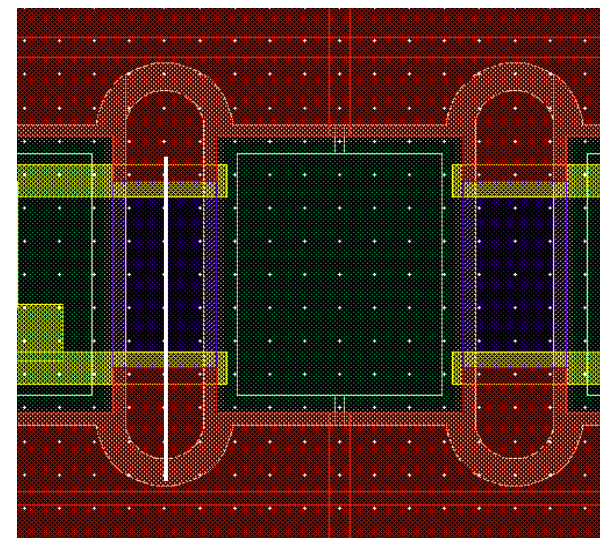
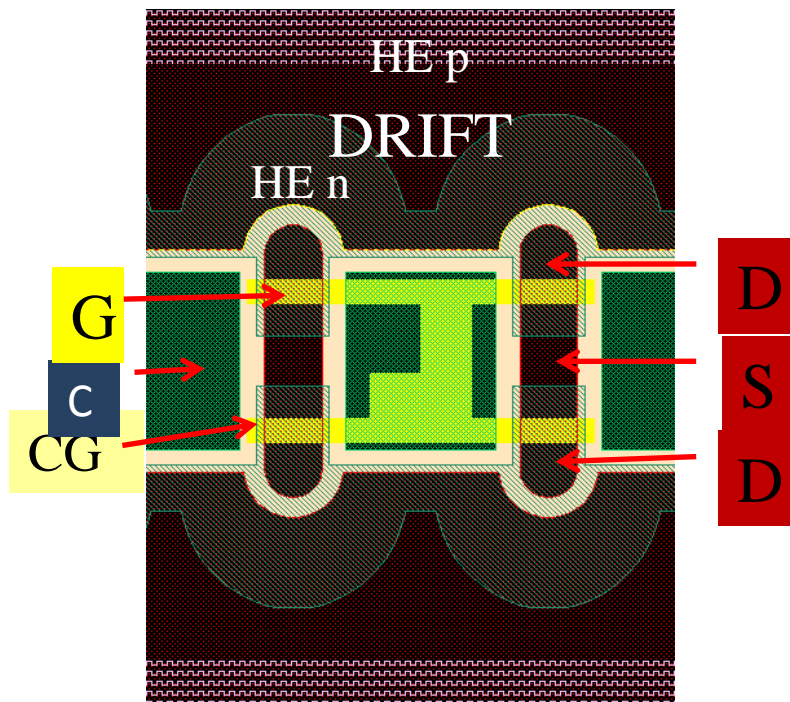
Very fast but
ro- electronics
Is bumpbonded
on top



What about the Belle design?

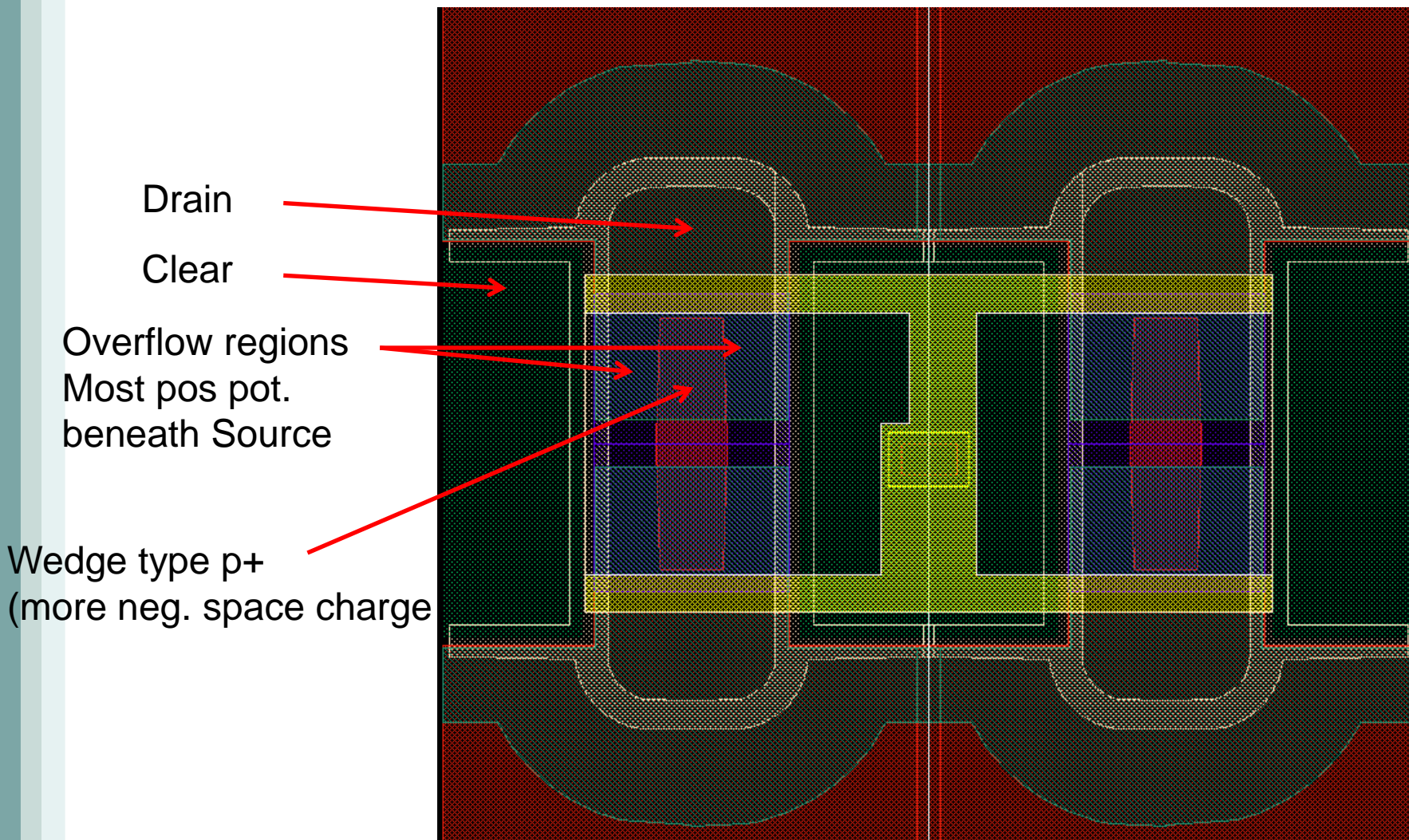
| | |
|---|------------|
| Thinned detector (50 μ m PXD6) | ok |
| Fast detector: row readout 4 fold row read out + DCD | 100ns !! |
| Low power consumption: (passive cooling) | ok |
| Pixel size (linear transistor) | acceptable |
| Single electron detection | ok |
| Dynamic range | no |

Depfet Design for Belle II

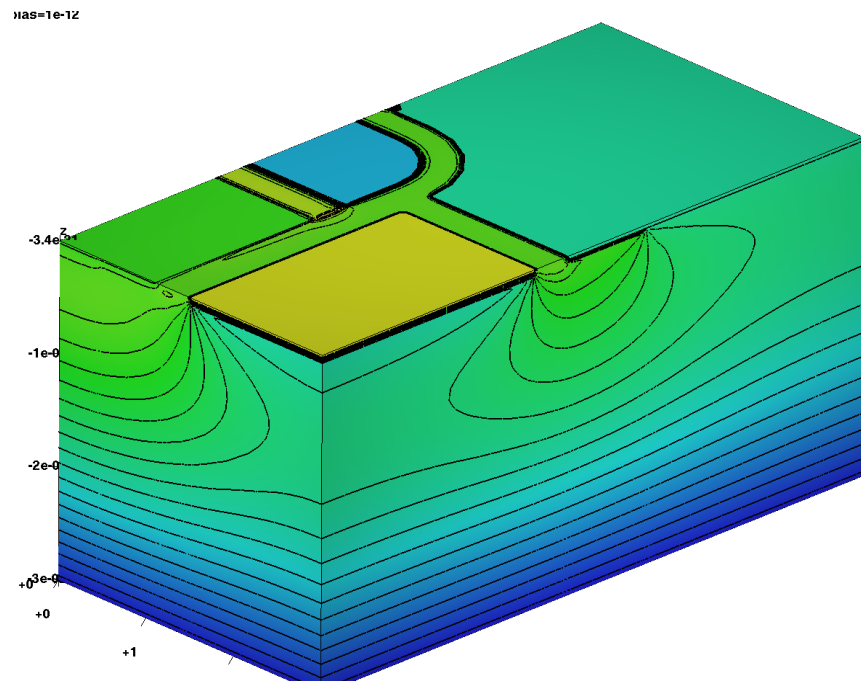
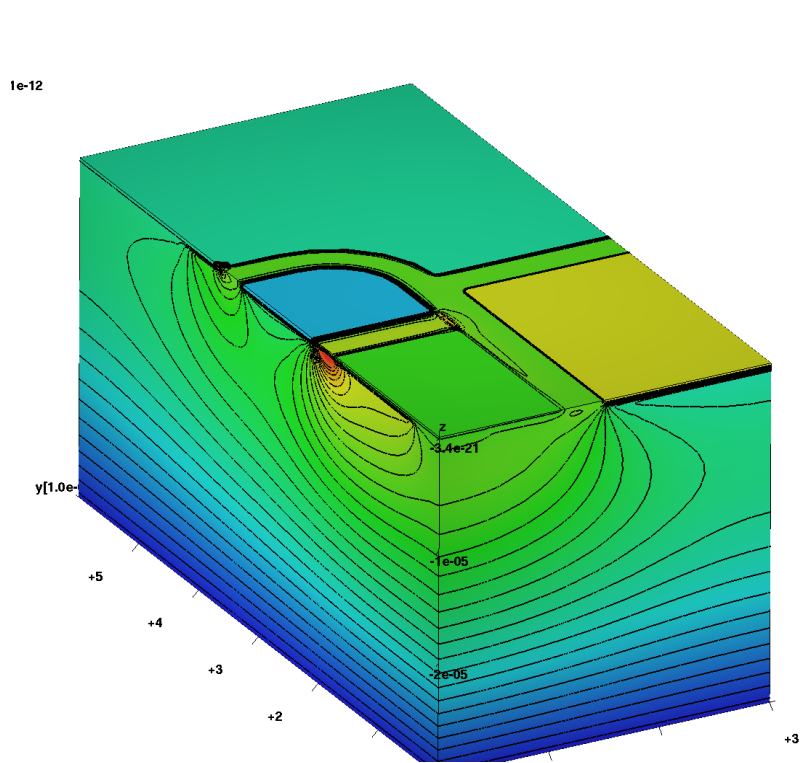


View on 4 pixel ($60 \times 60 \mu\text{m}^2$)

Similar to Belle but larger Sources and different doping



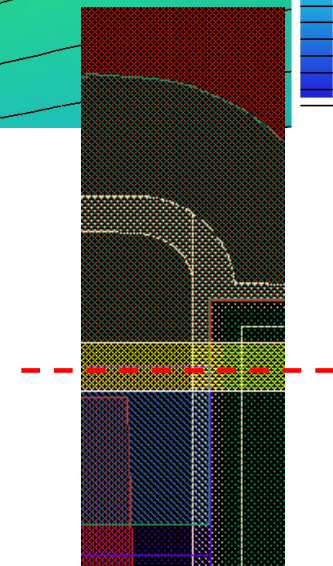
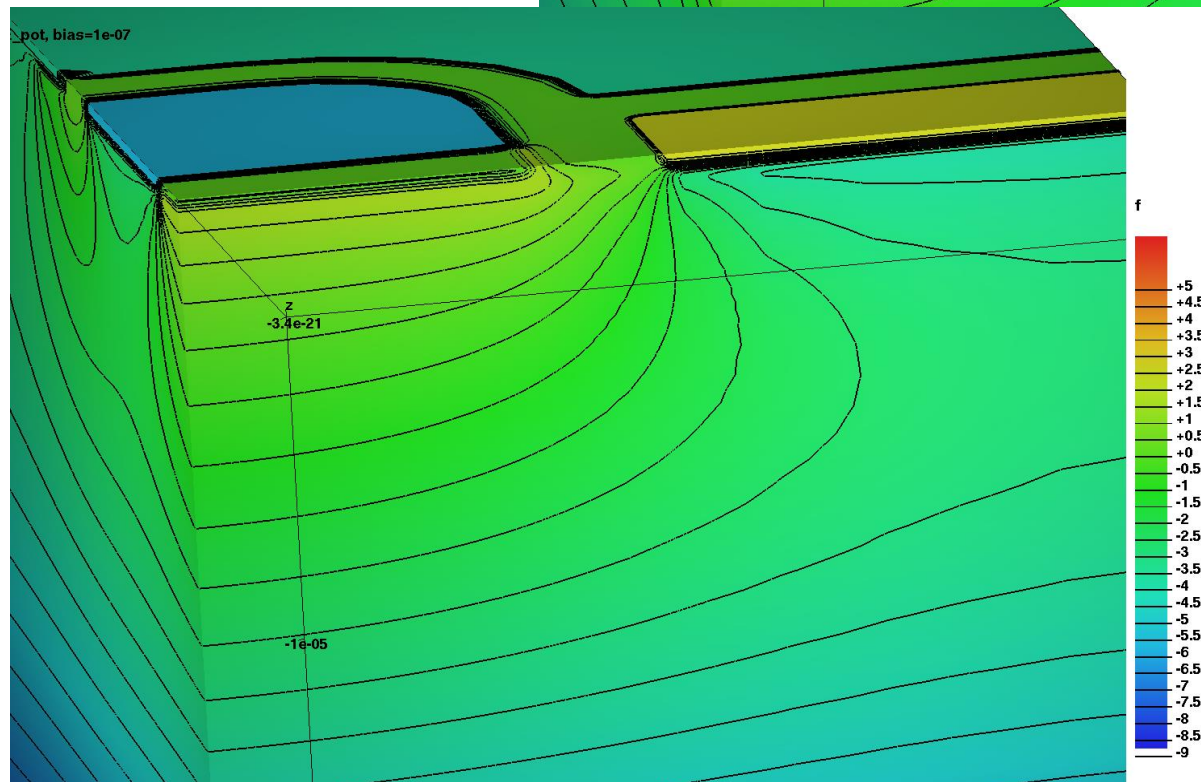
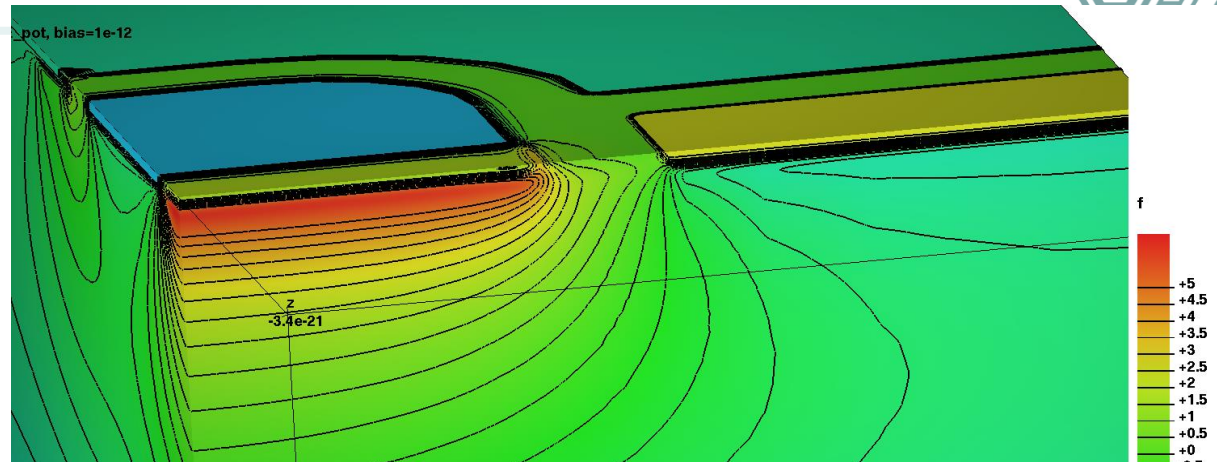
Potential Distribution during Collection (empty Internal Gate)



● Cut through Internal Gate

Empty

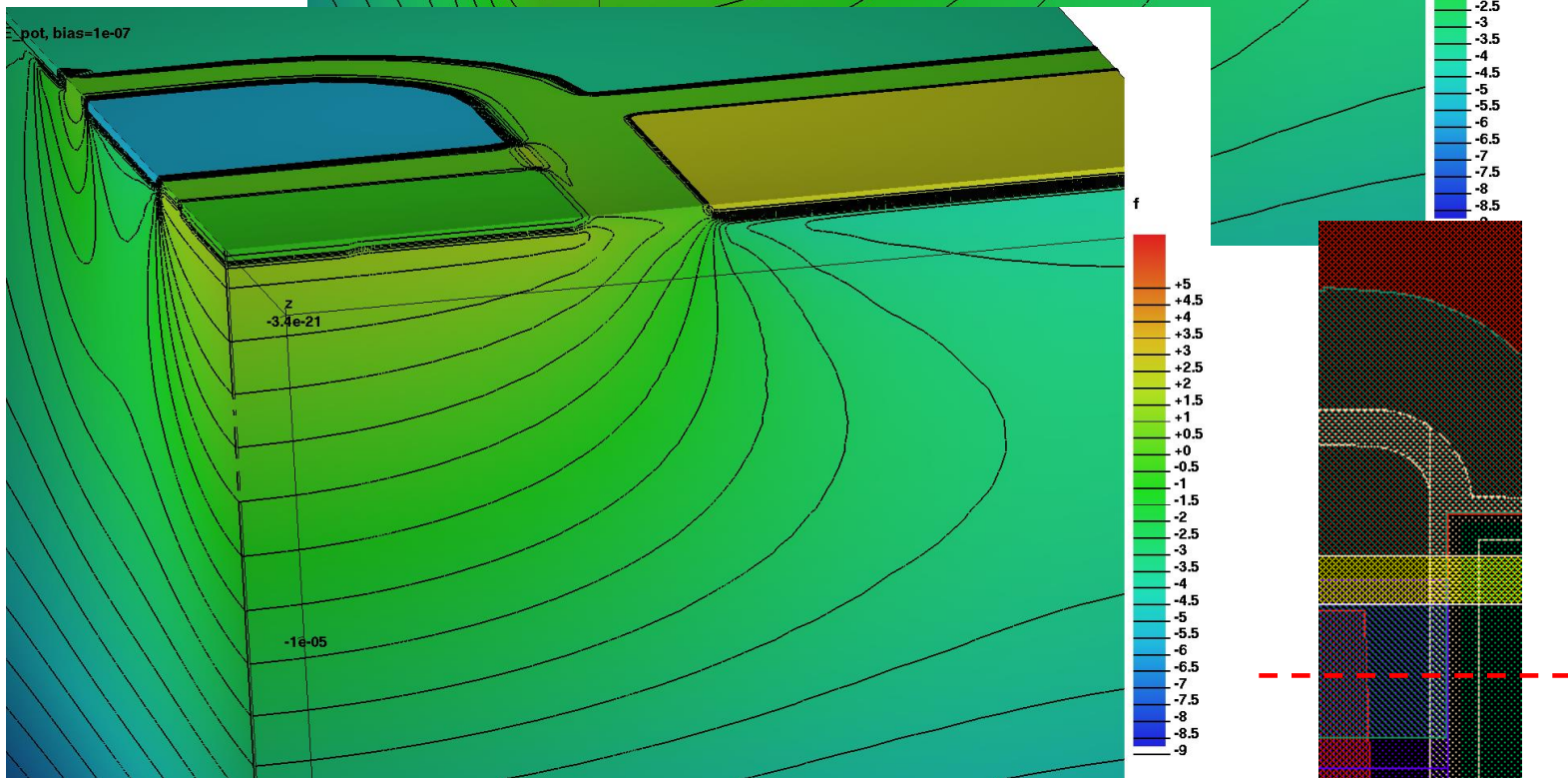
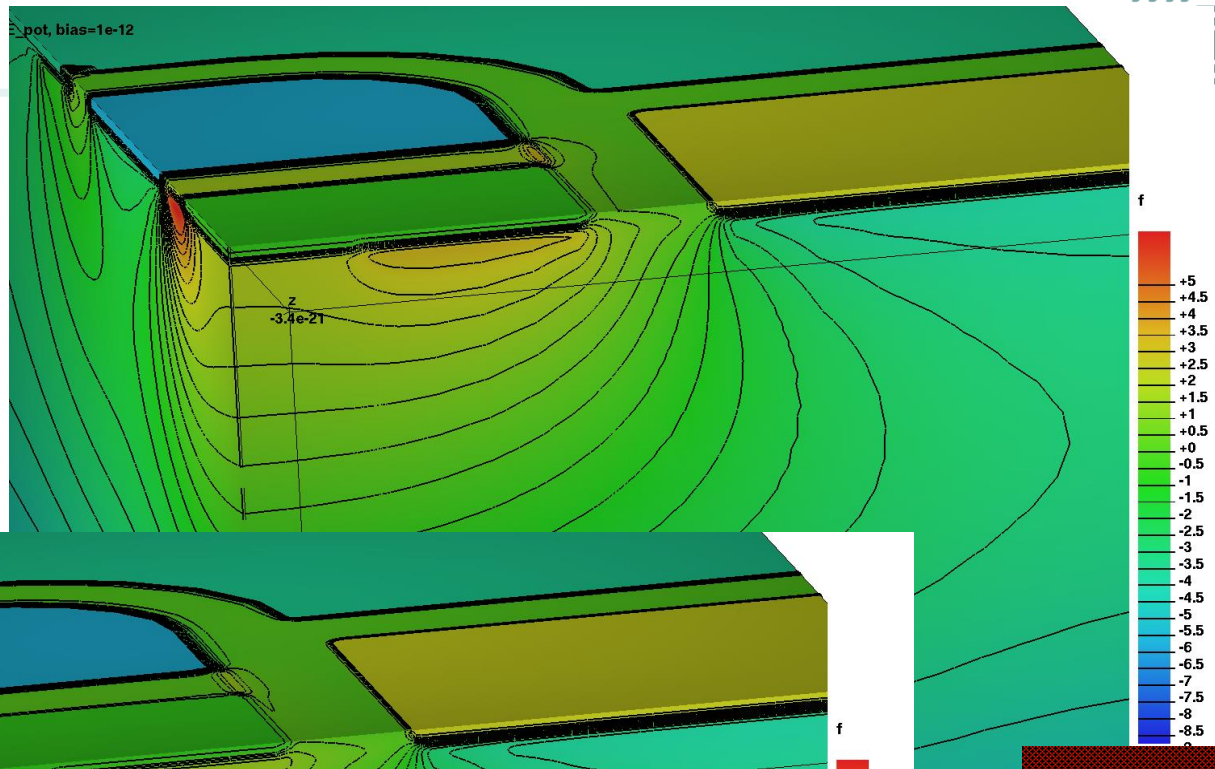
filled 400k e-



●
Cut through Source

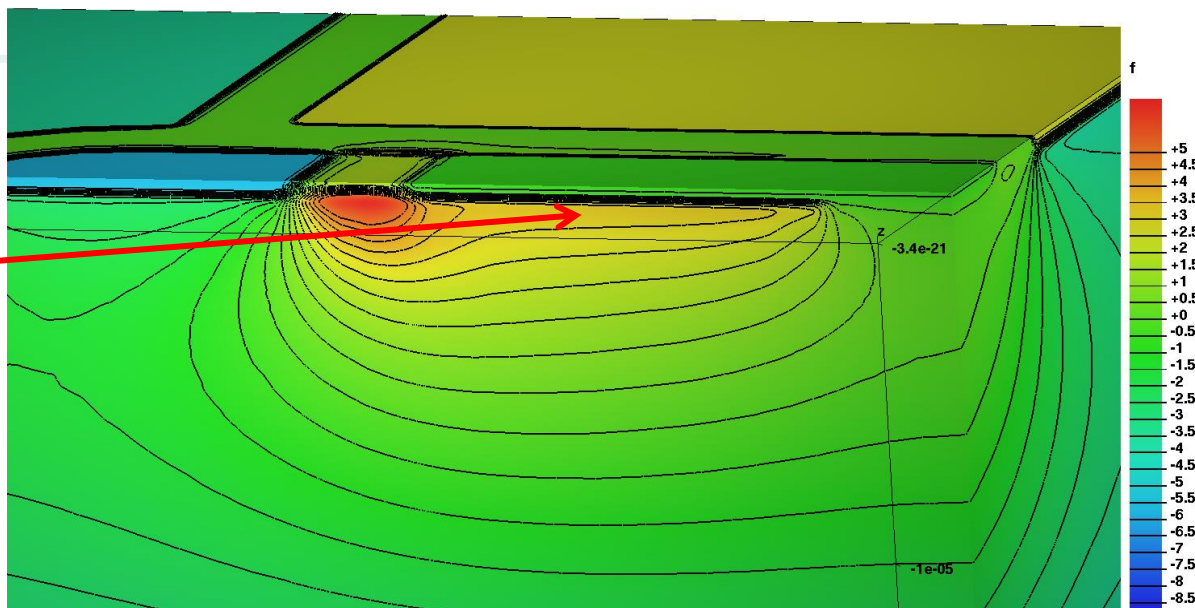
Empty

filled

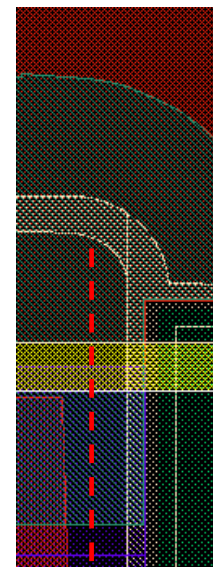
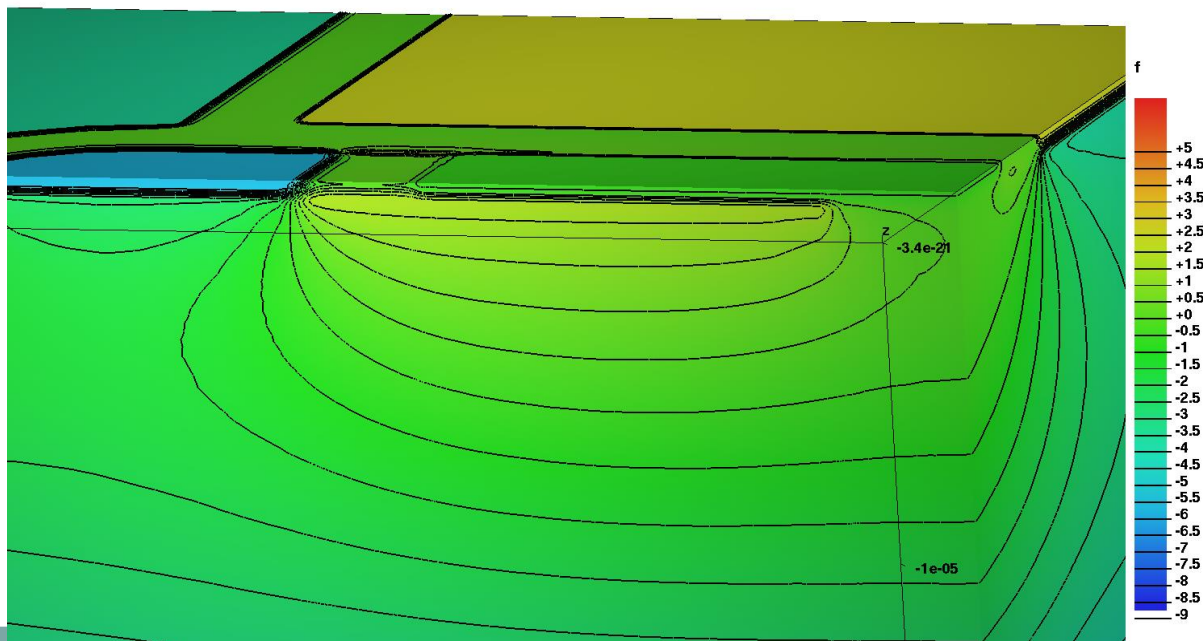


Modulation of potential by wedge

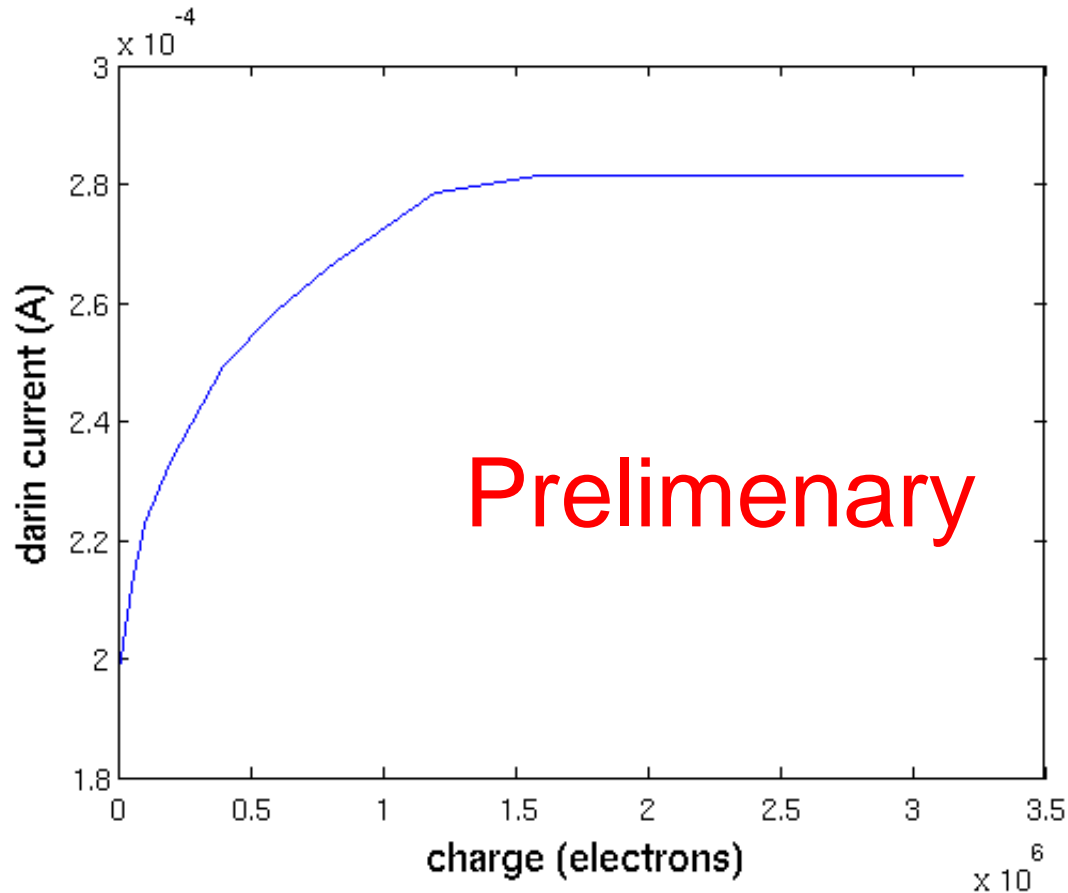
empty state



filled state
400k electrons



Simulated response curve

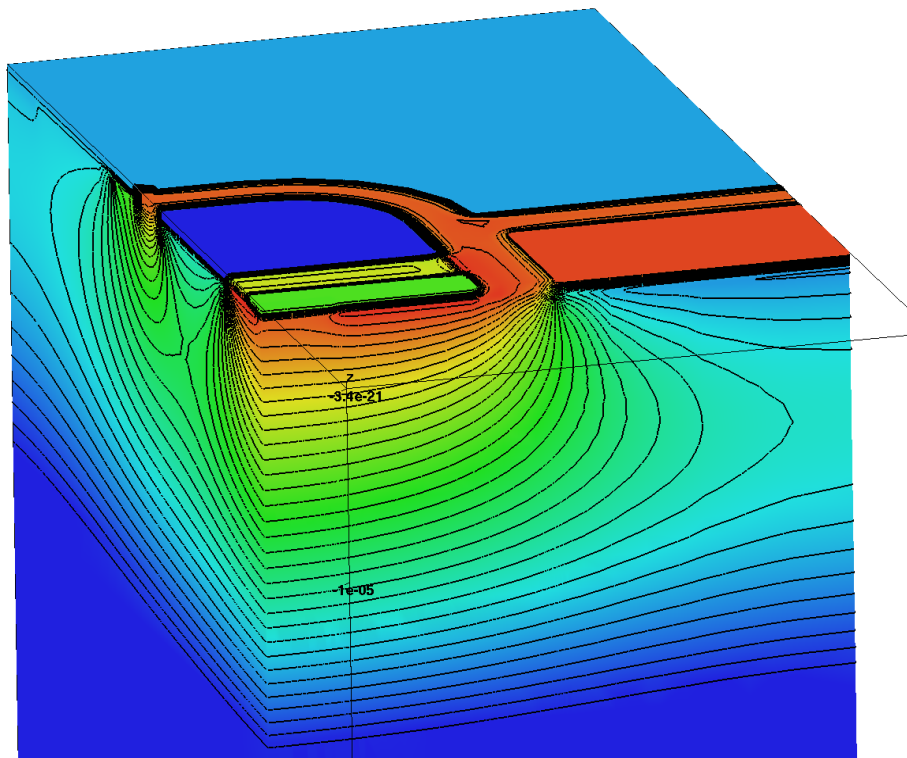
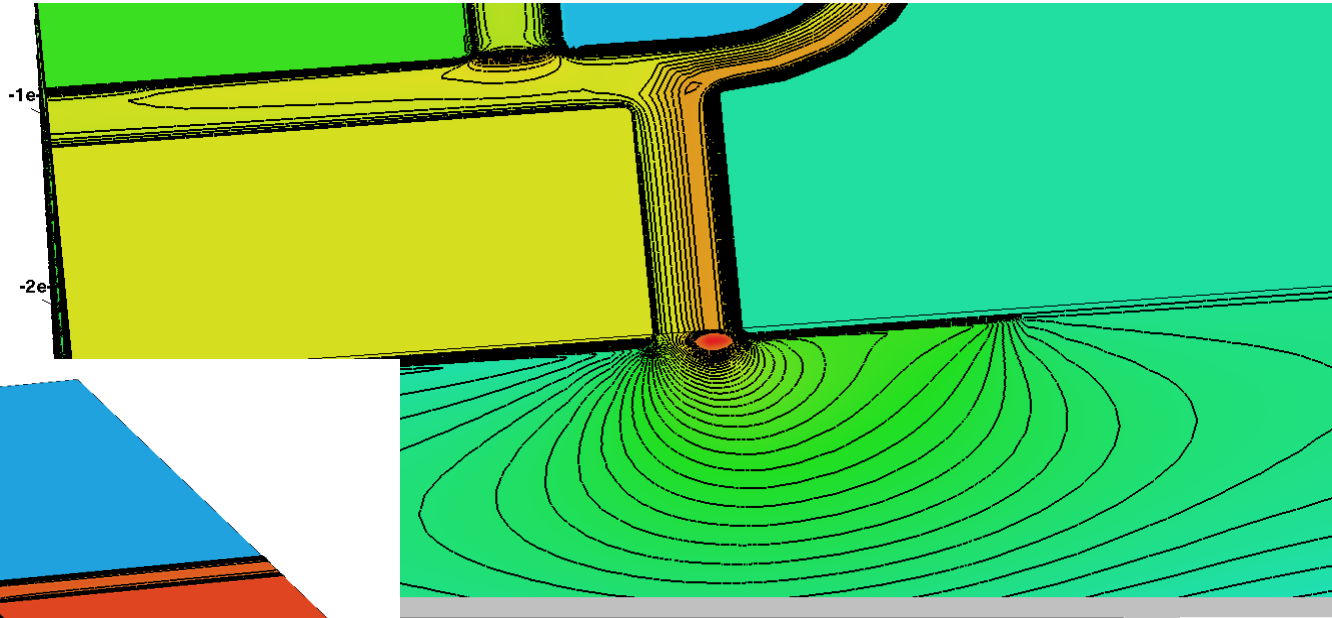


Saturation due to overflow in the Clear Regions

5. radiation tolerance

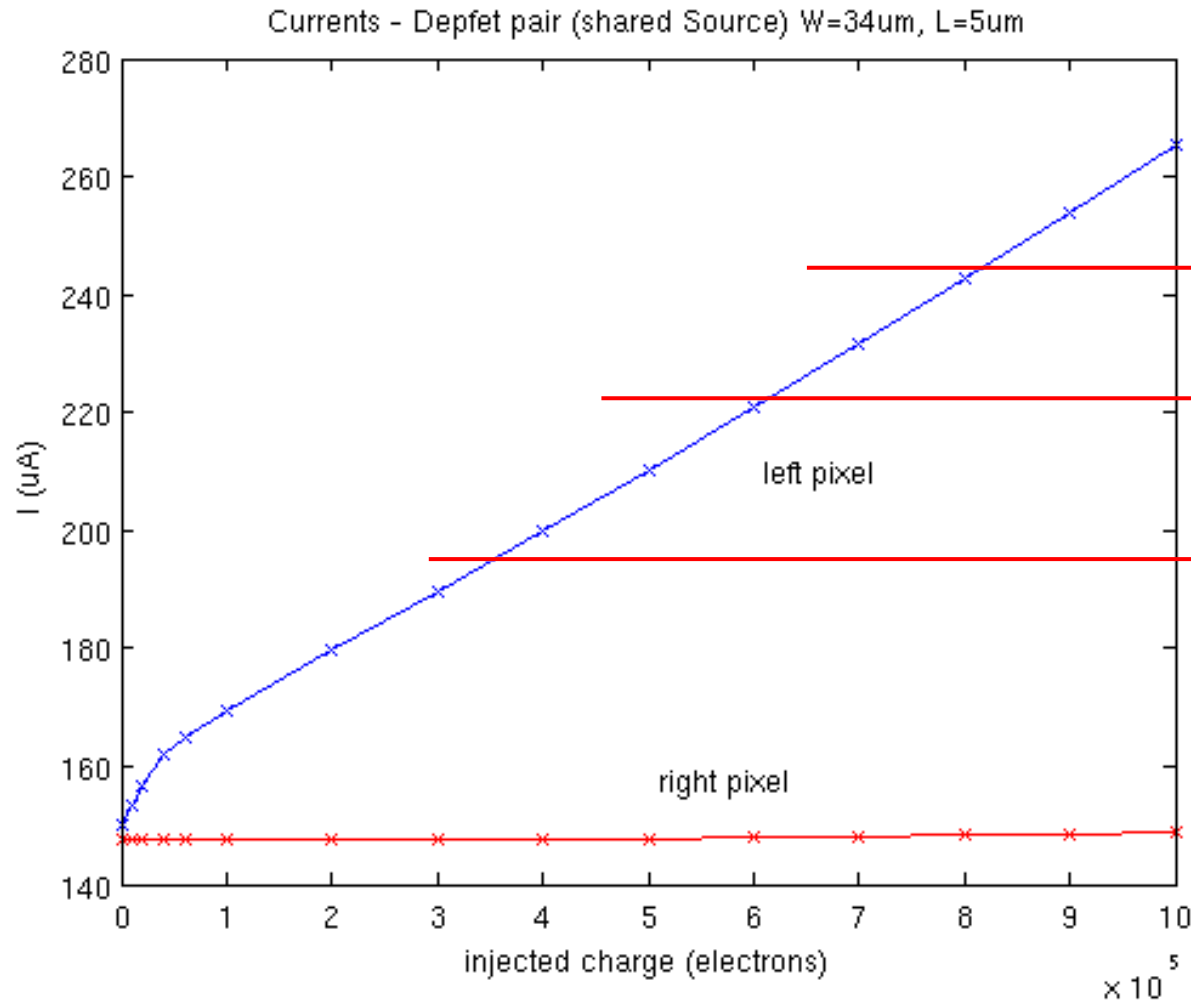
Real space detector sees a rather
homogeneous radiation level
(easier task)

- What is crucial ? Surface damage of oxides



Irradiated state:
 $V_{\text{clgate}} = 2.5\text{V}$

During irradiation - Charge handling capability



Overflow points
to Clear Gate

Fluence 1

Fluence 2

Fluence 3

● How to deal with radiation damage?

1. Oxide charge compensation by gate voltage adaption works only for homogeneous radiation
2. Annealing : Module should stands about 200°C
significant annealing of surface damage possible
(Master thesis: Martin Hensel)
3. Technology improvement

thinner oxides- studies ongoing

● Summary



DEPFET fulfills many requirements on a direct electron detector

Especially the 'Belle design' provides

low material, high speed, low noise, low power, small pixel

Not intrinsically given:

Dynamic range increase should work

Radiation hardness: work ongoing